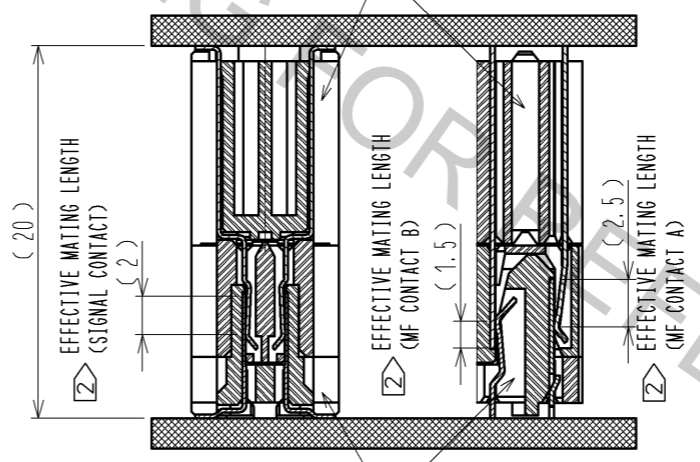
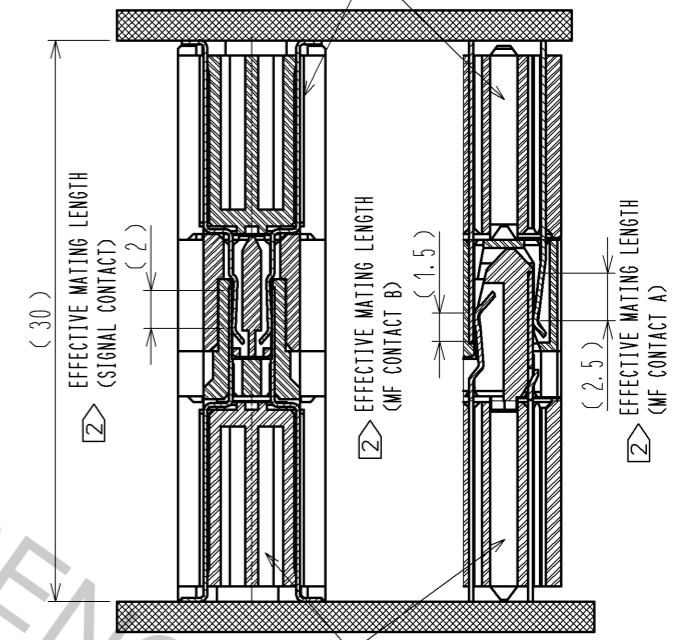


CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=20mm
FX18-60S-0.8SV20



CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=30mm
FX18-60S-0.8SV20



FX18-60P-0.8SV

FX18-60P-0.8SV10

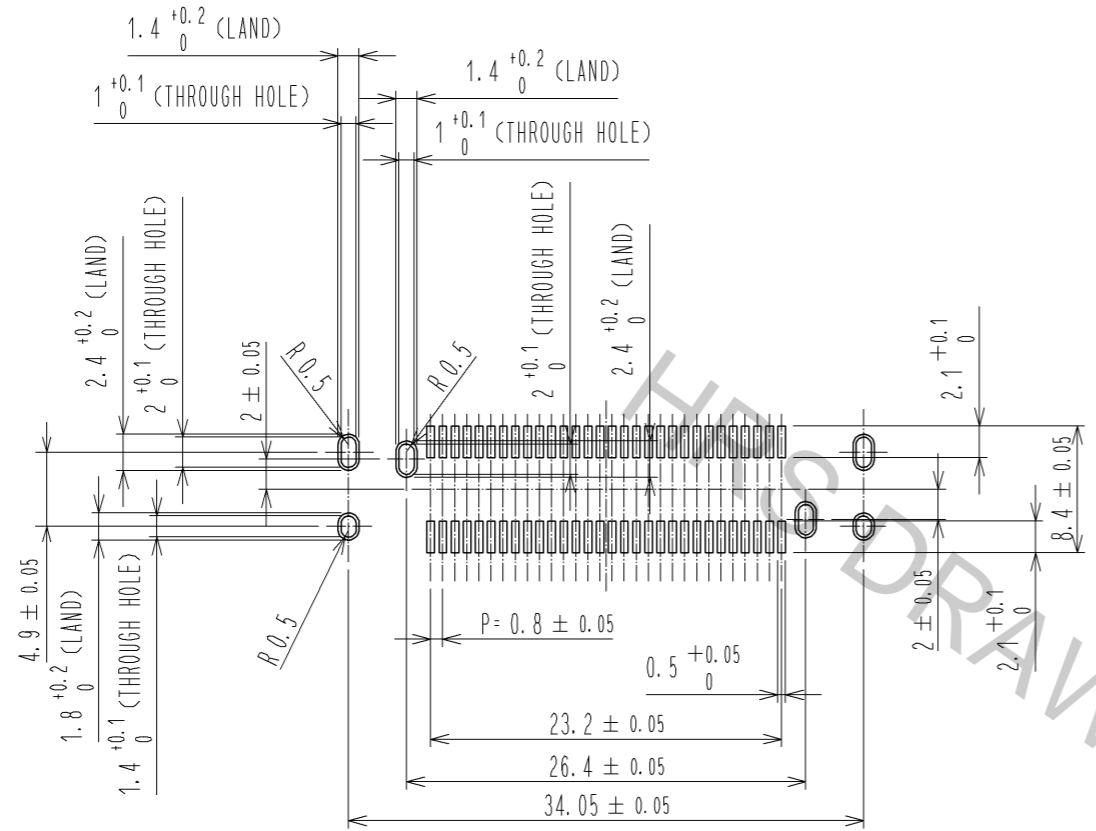
- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 ⑤ THIS IS PACKAGED IN TRAY. (60pcs/TRAY)
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm		5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm	
2	POLYAMIDE	BLACK UL94V-0		4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm	
1	POLYAMIDE	BLACK UL94V-0					

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△	APPROVED : HS. OKAWA 11.08.24 CHECKED : KI. HIROKAWA 11.08.24 DESIGNED : TH. SANO 11.08.24 DRAWN : TH. SANO 11.08.24			

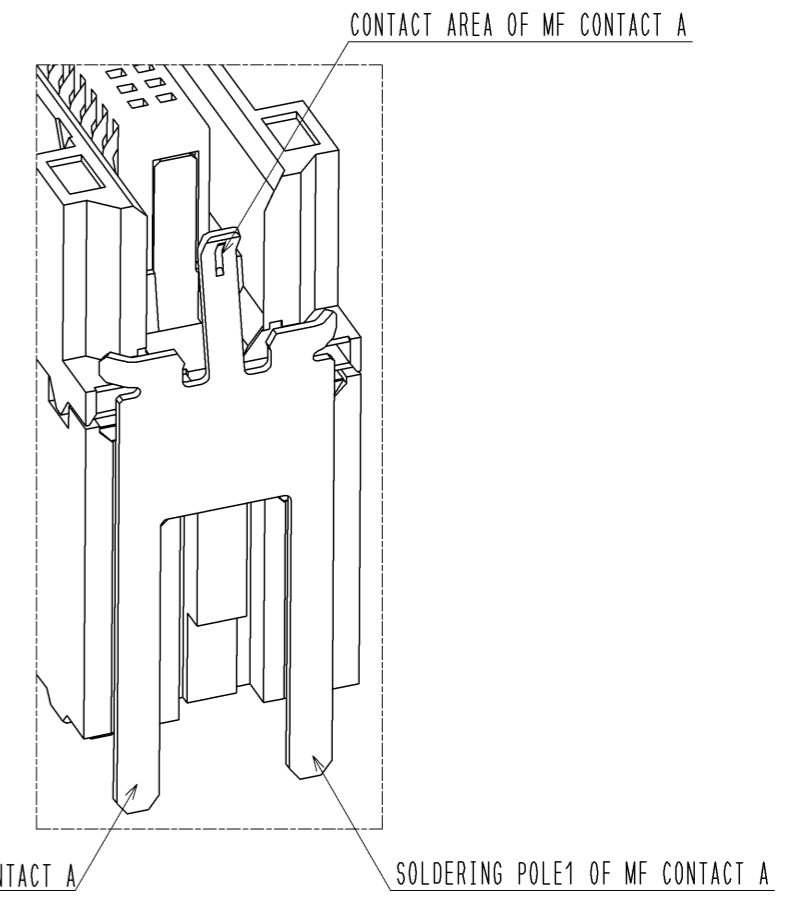
DRAWING NO.	PART NO.	CODE NO.
EDC3-334391-00	FX18-60S-0.8SV20	CL579-0031-3-00

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

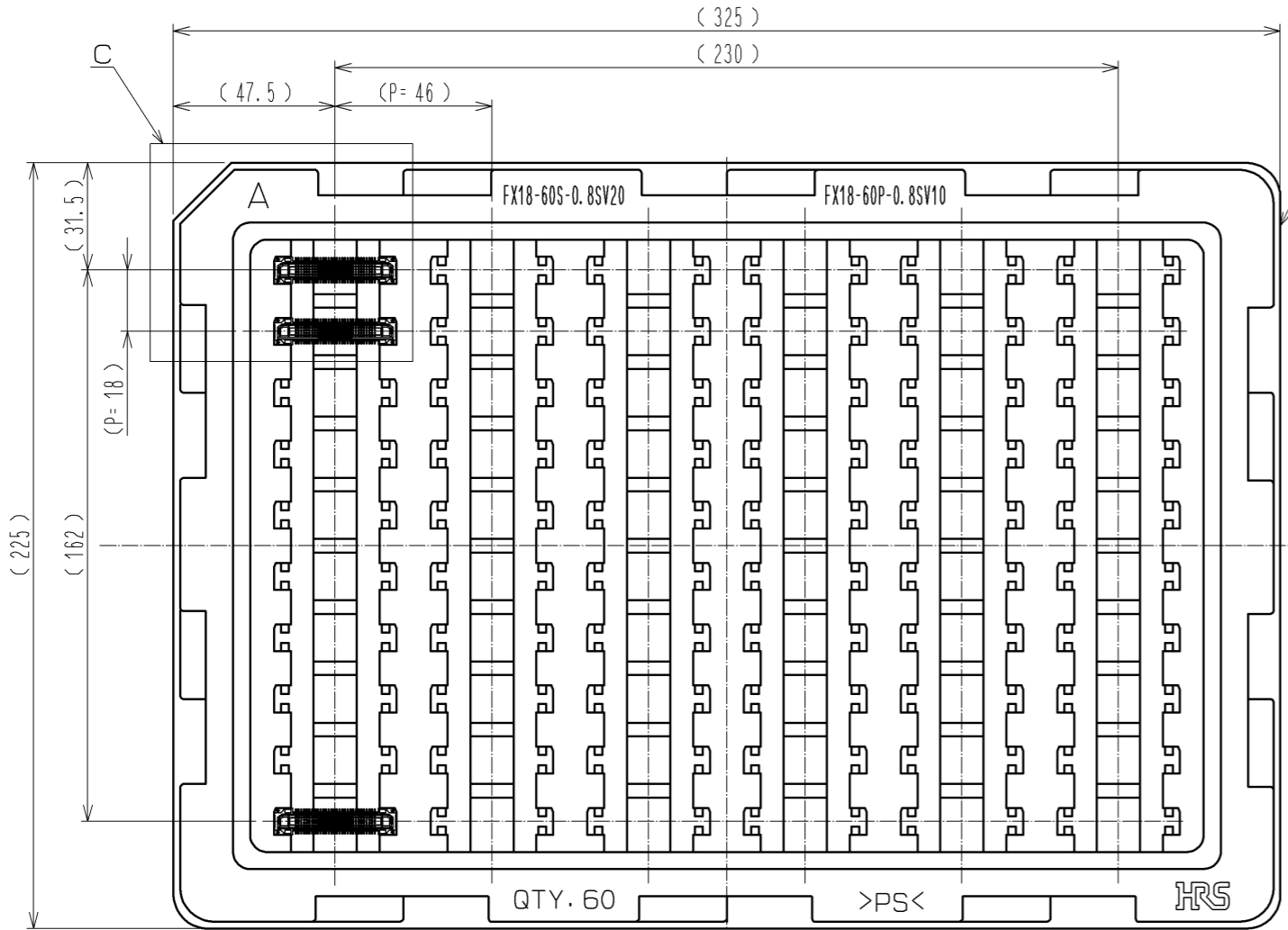


5 DRAWING FOR PACKING(1:2)

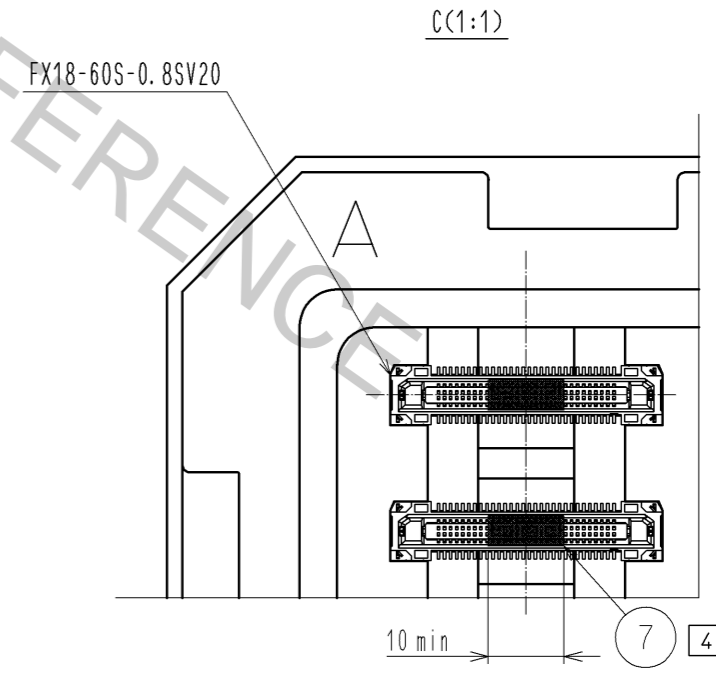
8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



6



HRS	DRAWING NO.	EDC3-334391-00
	PART NO.	FX18-60S-0.8SV20
	CODE NO.	CL579-0031-3-00
		△ 2/2